SEMICONDUCTOR DEVICE HAVING X-SHAPED DIE SUPPORT MEMBER AND METHOD FOR MAKING THE SAME

Abstract of the Disclosure

A semiconductor device (10) includes a lead frame (12) having tie bars (16). In one form of the invention, the tie bars are used to support a semiconductor die (20) to alleviate package cracking problems caused by stress and to provide a universal lead frame which is suitable for use with many different die sizes. In another embodiment, a semiconductor device (45) includes a lead frame (40) having a mini-flag (42) to accomplish these same objectives.

Fig. 1 accompanies this abstract.